

N-Ch MOSFET

General Description

The WSC5N20A is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSC5N20A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Product Summery

BVDSS	RDSON	ID
200V	0.6Ω	5A

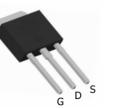
Applications

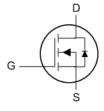
• Telecom 48V input Forward Converters

TO-251/ I-Pak Pin Configuration

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	200	V
V _{GS}	Gate-Source Voltage	±20	V
Ι _D	Continuous Drain Current	5	А
I _{DM}	Pulsed Drain Current	20	A
P _D	Total Power Dissipation	43	W
TJ,T _{STG}	Operating Junction and storage Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter		Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient (Steady State) ¹		50	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		35	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		3.5	°C/W



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	200			V
$\triangle BV_{DSS} / \triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!\mathbb{C}$, I_D=1mA		0.23		V/℃
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =30A		0.52	0.6	Ω
V _{GS(th)}	Gate Threshold Voltage	—V _{GS} =V _{DS} , I _D =250uA	1.2	1.7	2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-6.16		mV/℃
I _{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}200\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}25^\circ\!\!\mathrm{C}$			25	uA
		V _{DS} =160V , V _{GS} =0V , T _J =55℃			200	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm30V$, $V_{DS}=0V$			±100	nA

Dynamic @ TJ = 25°C (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
gfs	Forward Transconductance	V _{DS} =50V , I _D =2.9A	2.6			S
Qg	Total Gate Charge (4.5V)	V _{DS} =160V ,		15		
Q _{gs}	Gate-Source Charge	V _{GS} =10V ,		2.4		nC
Q _{gd}	Gate-Drain Charge	- I _D =2.9A		6.1		
T _{d(on)}	Turn-On Delay Time	V _{DD} =100V		6.4		
Tr	Rise Time	V _{GS} =10V		11		20
T _{d(off)}	Turn-Off Delay Time	R _G =24Ω		20		ns
T _f	Fall Time	I _D =2.9A		12		
C _{iss}	Input Capacitance	V _{DS} =25V		300		
Coss	Output Capacitance	V _{GS} =0V		53		pF
C _{rss}	Reverse Transfer Capacitance	f=1MHz		15		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	$V_G = V_D = 0V$, Force Current			5	А
V _{SD}	Diode Forward Voltage	$V_{GS}\text{=}0V$, $I_{S}\text{=}2.9A$, $T_{J}\text{=}25^{\circ}\!\!\!\mathrm{C}$			1.2	V

Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
E _{AS}	Single Pulse Avalanche Energy	VGS=10V,L=0.1mH,IAS=2.9A			46	mJ
E _{AR}	Repetitive Avalanche Energy	VGS=10V,L=0.1mH,IAS=2.9A			4.3	mJ

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}\text{=}100V, V_{\text{GS}}\text{=}10V, L\text{=}0.1\text{mH}, I_{\text{AS}}\text{=}2.9\text{A}$

4. The power dissipation is limited by 175°C junction temperature

5.The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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Typical Characteristics

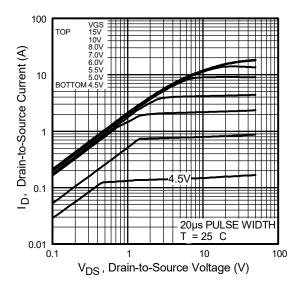


Fig 1. Typical Output Characteristics

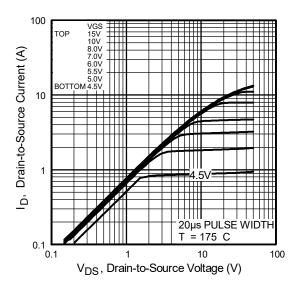


Fig 2. Typical Output Characteristics

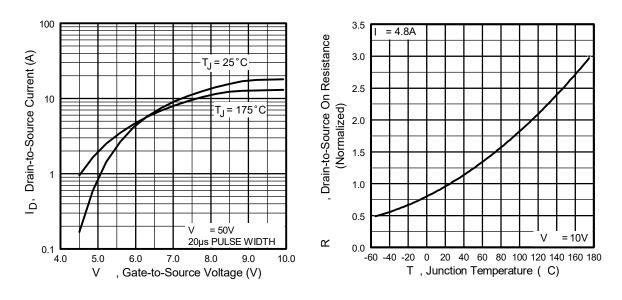


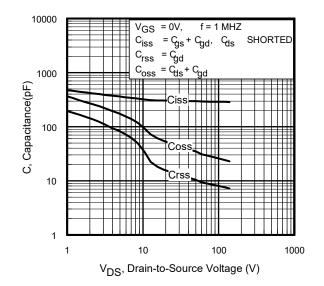
Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance Vs. Temperature

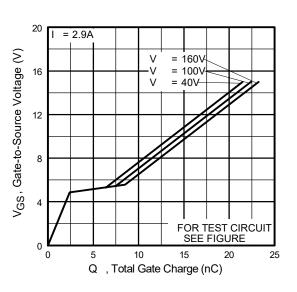


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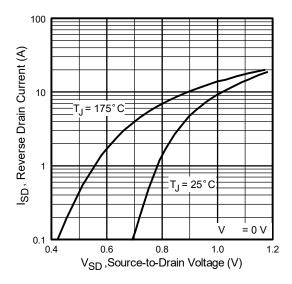


Fig 7. Typical Source-Drain Diode Forward Voltage

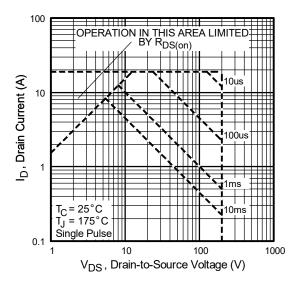
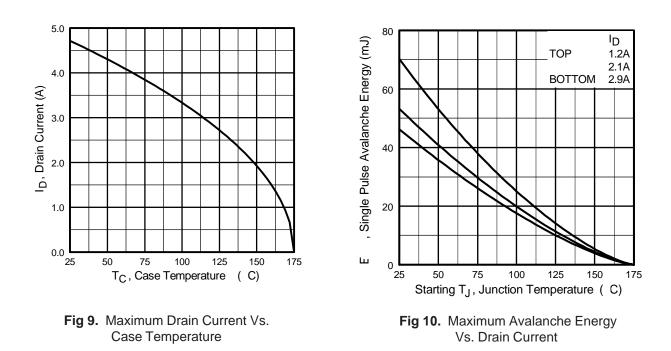


Fig 8. Maximum Safe Operating Area



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10 D = 0.50 Thermal Response (Z 1 0.20 0.10 0.05 PDM 0.1 0.02 0.01 SINGLE PULSE (THERMAL RESPONSE) Notes: 1. Duty factor D = t / t_2 2. Peak T = P $_{DM}$ x Z_{thJC} + T_{C} 0.01 0.000001 0.0001 0.001 0.01 0.00001 0.1 t , Rectangular Pulse Duration (sec)

Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



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